

IN THE SPECIFICATION

Please replace paragraph starting on line 5, page 10 of the specification with the following amended paragraph:

As shown in FIGS. 5, 6, 8, and 9, the auxiliary substrate for hierarchical mounting 14 is made of a glass epoxy resin and includes inside thereof, from top to bottom, a signal layer 31, a power supply layer 32, and a ground layer 33. The auxiliary substrate for hierarchical mounting 14 further includes a through hole group 34, and has the pad group 23 of the numerous semiconductor component mounting pads 23a used for mounting of the semiconductor component 16 and wiring patterns 35 formed on the upper surface 14e and the pad group 36 of the numerous printed wiring board mounting pads 36a used for mounting on the printed wiring board 11 formed on the lower surface 14f. A pitch p2 between each adjacent ones of the pads 36a is approximately twice a pitch p1 between each adjacent ones of the pads 23a so that the pads 36a are more dispersed than the pads 23a. A reason for this will be later described. A number N1 of pads 36a is smaller than a number N2 of the pads 23a. A reason for this will also be described later.